Energy efficient and isolated CANopen interface

Project Title: Designed for: Public Release

Assembly Variant: 001

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Drawn By: Engineer: Thomas Mauer

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Revision History

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Orderable: ChangeMe!

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Variant/Label Table

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Assembly Note ZZ1
These assemblies are ESD sensitive, ESD precautions shall be observed.

Assembly Note ZZ2
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Assembly Note ZZ4
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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